TSMC-01-787

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December 17, 2003

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: Serial No. 10/680,578 10/07/03

Tze-Liang Lee et al.

PAD STRUCTURE FOR STRESS RELIEF

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation In An Application.

The following Patents and/or Publications are submitted to comply with the duty of disclosure under CFR 1.97-1.99 and 37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on December 19, 2003.

Stephen B. Ackerman, Reg.# 37761

Signature/Date 12/19/03

U.S. Patent 5,567,655 to Rostoker et al., "Method for Forming Interior Bond Pads Having Zig-Zag Linear Arrangement," discloses a technique for reducing thermally induced stress on bonding pads in semiconductor devices.

U.S. Patent 5,643,830 to Rostoker et al., "Process for Manufacturing Off-Axis Power Branches for Interior Bond Pad Arrangements," discloses a technique for improving power distribution to a semiconductor die while simultaneously reducing thermally induced stresses.

U.S. Patent 5,075,254 to Robinson et al., "Method and Apparatus for Reducing Die Stress," discloses a slotted metallic die attach pad for attachment of a semiconductor die to form a die assembly that demonstrates reduced die attach stress.

U.S. Patent 6,165,886 to Lin et al., "Advanced IC Bonding Pad Design for Preventing Stress Induced Passivation Cracking and Pad Delimitation Through Stress Bumper Pattern and Dielectric Pin-On Effect," discloses a bonding pad design, utilizing stress bumpers on the pad periphery, which can prevent passivation cracking and pad delamination during high temperature processing.

Sincerely,

Stephen B. Ackerman, Reg. #37761

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Form PTO-1449

INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

Docket Number (Optional): TSMC-01-787
Application Number: 10/680,578
Applicant: Tze-Liang Lee et al.
Filing Date: 10/07/03
Group Art Unit:

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	5567655	10/22/96	Rostoker et al.	437	209	6/5/95
	5643830	7/1/97	Rostoker et al.	437	180	1/23/95
	5075254	12/24/91	Robinson et al.	437	209	7/13/90
	6165886	12/26/00	Lin et al.	438	612	11/17/98

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation YES	Translation NO

OTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, Etc.)*

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.